

# SGM721/SGM722/SGM723/SGM724

## 11MHz, Rail-to-Rail I/O CMOS Operational Amplifiers

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### GENERAL DESCRIPTION

The SGM721 (single), SGM722 (dual), SGM723 (single with shutdown) and SGM724 (quad) are low noise, low voltage and low power operational amplifiers, that can be designed into a wide range of applications. The SGM721/2/3/4 have a high gain-bandwidth product of 11MHz and a slew rate of 8.5V/ $\mu$ s. The SGM723 has a power-down disable feature that reduces the supply current to less than 1 $\mu$ A.

The SGM721/2/3/4 are designed to provide optimal performance in low voltage and low noise systems. They provide rail-to-rail output swing into heavy loads. The input common mode voltage range includes ground, and the maximum input offset voltage is 4mV for SGM721/2/3/4. They are specified over the extended industrial temperature range (-40°C to +125°C). The operating supply range is from 2.1V to 5.5V.

The single version, SGM721 is available in Green SC70-5, SOT-23-5 and SOIC-8 packages. SGM723 is available in Green SOT-23-6 and SOIC-8 packages. The dual version SGM722 is available in Green SOIC-8, MSOP-8 and TSSOP-8 packages. The quad version SGM724 is available in Green SOIC-14 and TSSOP-14 packages.

### FEATURES

- Rail-to-Rail Input and Output
- Input Offset Voltage: 4mV (MAX)
- High Gain-Bandwidth Product: 11MHz
- High Slew Rate: 8.5V/ $\mu$ s
- Settling Time to 0.1% with 2V Step: 0.21 $\mu$ s
- Overload Recovery Time: 0.6 $\mu$ s
- Low Noise: 8.5nV/ $\sqrt{\text{Hz}}$  at 10kHz
- Supply Voltage Range: 2.1V to 5.5V
- Input Voltage Range: -0.1V to 5.6V with  $V_S = 5.5V$
- Low Power:
  - SGM721/3: 1.2mA (TYP)
  - SGM722/4: 1.1mA/Amplifier (TYP)
  - SGM723 Less than 1 $\mu$ A when Disabled
- -40°C to +125°C Operating Temperature Range
- Small Packaging:
  - SGM721 Available in Green SC70-5, SOT-23-5 and SOIC-8 Packages
  - SGM722 Available in Green MSOP-8, SOIC-8 and TSSOP-8 Packages
  - SGM723 Available in Green SOT-23-6 and SOIC-8 Packages
  - SGM724 Available in Green TSSOP-14 and SOIC-14 Packages

### APPLICATIONS

Sensors  
Audio  
Active Filters  
A/D Converters  
Communications  
Test Equipment  
Cellular and Cordless Phones  
Laptops and PDAs  
Photodiode Amplification  
Battery-Powered Instrumentation

**PACKAGE/ORDERING INFORMATION**

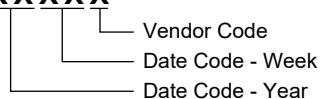
MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM721	SC70-5	-40°C to +125°C	SGM721XC5/TR	721	Tape and Reel, 3000
	SOT-23-5	-40°C to +125°C	SGM721XN5/TR	721	Tape and Reel, 3000
	SOIC-8	-40°C to +125°C	SGM721XS/TR	SGM721XS XXXXX	Tape and Reel, 2500
SGM722	MSOP-8	-40°C to +125°C	SGM722XMS/TR	SGM722 XMS XXXXX	Tape and Reel, 3000
	SOIC-8	-40°C to +125°C	SGM722XS/TR	SGM722XS XXXXX	Tape and Reel, 2500
	TSSOP-8	-40°C to +125°C	SGM722XTS8G/TR	SGM722 XTS8 XXXXX	Tape and Reel, 4000
SGM723	SOT-23-6	-40°C to +125°C	SGM723XN6/TR	723	Tape and Reel, 3000
	SOIC-8	-40°C to +125°C	SGM723XS/TR	SGM723XS XXXXX	Tape and Reel, 2500
SGM724	SOIC-14	-40°C to +125°C	SGM724XS14/TR	SGM724XS14 XXXXX	Tape and Reel, 2500
	TSSOP-14	-40°C to +125°C	SGM724XTS14/TR	SGM724 XTS14 XXXXX	Tape and Reel, 3000

**MARKING INFORMATION**

NOTE: XXXXX = Date Code and Vendor Code.

**SOIC-8/MSOP-8/TSSOP-8/SOIC-14/TSSOP-14**

**XXXXX**



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, +V <sub>S</sub> to -V <sub>S</sub> .....	7V
Input Common Mode Voltage Range .....	(-V <sub>S</sub> ) - 0.3V to (+V <sub>S</sub> ) + 0.3V
Package Thermal Resistance @ T <sub>A</sub> = +25°C	
SC70-5, θ <sub>JA</sub> .....	333°C/W
SOT-23-5, θ <sub>JA</sub> .....	190°C/W
SOT-23-6, θ <sub>JA</sub> .....	190°C/W
SOIC-8, θ <sub>JA</sub> .....	125°C/W
MSOP-8, θ <sub>JA</sub> .....	216°C/W
Junction Temperature.....	+150°C
Storage Temperature Range .....	-65°C to +150°C
Lead Temperature (Soldering, 10s).....	+260°C
ESD Susceptibility	
HBM (SGM721/2/4) .....	8000V
HBM (SGM723) .....	4000V
MM.....	400V
CDM .....	1000V

**RECOMMENDED OPERATING CONDITIONS**

Operating Temperature Range .....	-40°C to +125°C
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**OVERSTRESS CAUTION**

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

**ESD SENSITIVITY CAUTION**

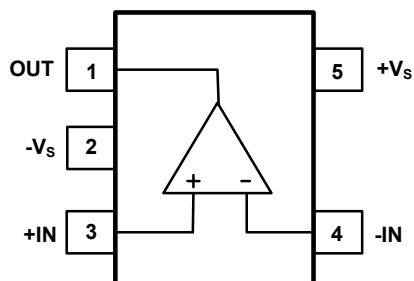
This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

**DISCLAIMER**

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

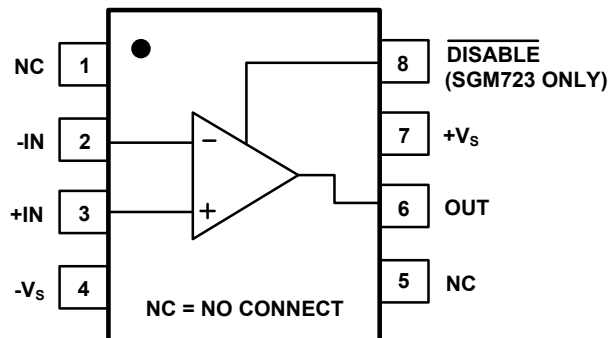
**PIN CONFIGURATIONS**

**SGM721 (TOP VIEW)**



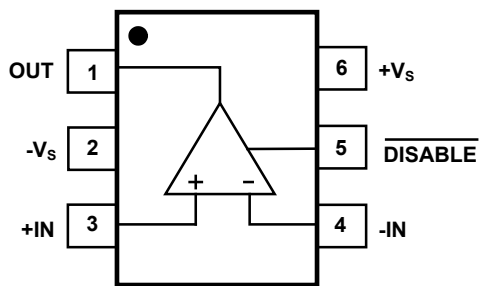
**SC70-5/SOT-23-5**

**SGM721/723 (TOP VIEW)**



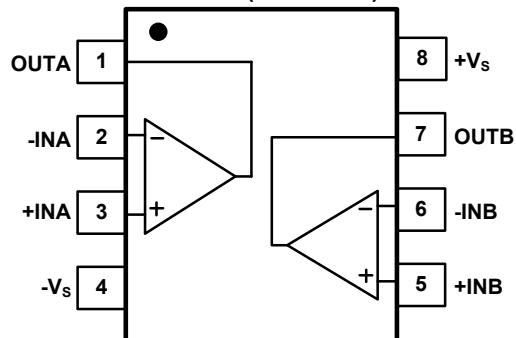
**SOIC-8**

**SGM723 (TOP VIEW)**



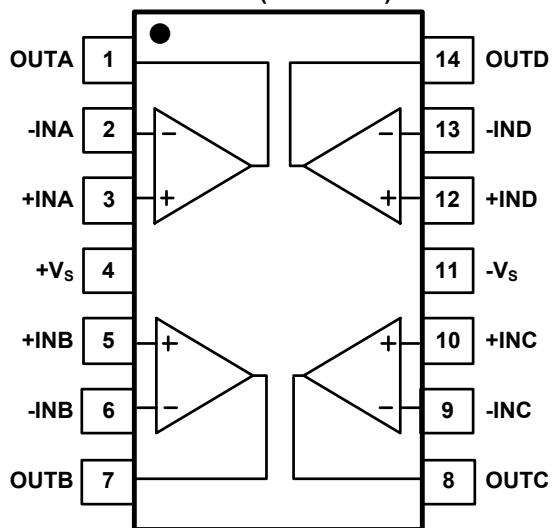
**SOT-23-6**

**SGM722 (TOP VIEW)**



**SOIC-8/MSOP-8/TSSOP-8**

**SGM724 (TOP VIEW)**



**TSSOP-14/SOIC-14**

**ELECTRICAL CHARACTERISTICS**

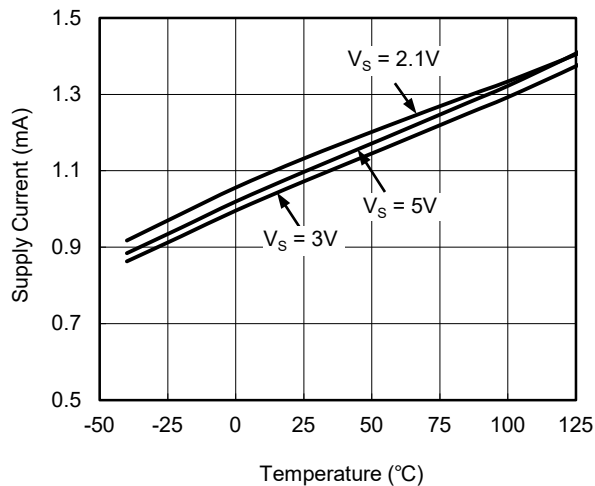
(At T<sub>A</sub> = +25°C, V<sub>S</sub> = +5V, V<sub>CM</sub> = V<sub>S</sub>/2, R<sub>L</sub> = 600Ω, unless otherwise noted.)

PARAMETER	CONDITIONS	SGM721/2/3/4						
		TYP	MIN/MAX OVER TEMPERATURE				UNITS	MIN/MAX
		+25°C	+25°C	-40°C to +85°C	-40°C to +125°C			
<b>INPUT CHARACTERISTICS</b>								
Input Offset Voltage (V <sub>OS</sub> )		1.5	4	4.3	4.6	mV	MAX	
Input Bias Current (I <sub>B</sub> )		1				pA	TYP	
Input Offset Current (I <sub>OS</sub> )		1				pA	TYP	
Input Common Mode Voltage Range (V <sub>CM</sub> )	V <sub>S</sub> = 5.5V	-0.1 to 5.6				V	TYP	
Common Mode Rejection Ratio (CMRR)	V <sub>S</sub> = 5.5V, V <sub>CM</sub> = -0.1V to 4V	83	67	66	65	dB	MIN	
	V <sub>S</sub> = 5.5V, V <sub>CM</sub> = -0.1V to 5.6V	75	60	59	56	dB	MIN	
Open-Loop Voltage Gain (A <sub>OL</sub> )	R <sub>L</sub> = 600Ω, V <sub>OUT</sub> = 0.15V to 4.85V	89	82	74	71	dB	MIN	
	R <sub>L</sub> = 10kΩ, V <sub>OUT</sub> = 0.05V to 4.95V	102	96	85	83	dB	MIN	
Input Offset Voltage Drift (ΔV <sub>OS</sub> /ΔT)		2.1				μV/°C	TYP	
<b>OUTPUT CHARACTERISTICS</b>								
Output Voltage Swing from Rail	R <sub>L</sub> = 600Ω	0.076				V	TYP	
	R <sub>L</sub> = 10kΩ	0.006				V	TYP	
Output Current (I <sub>OUT</sub> )		67	52	42	36	mA	MIN	
Closed-Loop Output Impedance	f = 1MHz, G = 1	8.5				Ω	TYP	
<b>POWER-DOWN DISABLE (SGM723 ONLY)</b>								
Turn-On Time		1.1				μs	TYP	
Turn-Off Time		0.3				μs	TYP	
DISABLE Voltage-Off			0.8			V	MAX	
DISABLE Voltage-On			2			V	MIN	
<b>POWER SUPPLY</b>								
Operating Voltage Range		2.1	2.1	2.1	2.1	V	MIN	
		5.5	5.5	5.5	5.5	V	MAX	
Power Supply Rejection Ratio (PSRR)	V <sub>S</sub> = +2.1V to +5.5V, V <sub>CM</sub> = (-V <sub>S</sub> ) + 0.5V	82	68	67	64	dB	MIN	
Quiescent Current/Amplifier (I <sub>Q</sub> )	SGM722/4 I <sub>OUT</sub> = 0	1.10	1.40	1.60	1.75	mA	MAX	
	SGM721/3 I <sub>OUT</sub> = 0	1.2	1.5	1.7	1.85	mA	MAX	
Supply Current when Disabled (SGM723 only)		0.5	8	9	10	μA	MAX	
<b>DYNAMIC PERFORMANCE</b>								
Gain-Bandwidth Product (GBP)		11				MHz	TYP	
Phase Margin (φ <sub>O</sub> )		62				°	TYP	
Full Power Bandwidth (BW <sub>P</sub> )	< 1% distortion	400				kHz	TYP	
Slew Rate (SR)	G = 1, 2V output step	8.5				V/μs	TYP	
Settling Time to 0.1% (t <sub>S</sub> )	G = 1, 2V output step	0.21				μs	TYP	
Overload Recovery Time	V <sub>IN</sub> × G = V <sub>S</sub>	0.6				μs	TYP	
<b>NOISE PERFORMANCE</b>								
Input Voltage Noise Density (e <sub>n</sub> )	f = 1kHz	12.5				nV/√Hz	TYP	
	f = 10kHz	8.5				nV/√Hz	TYP	

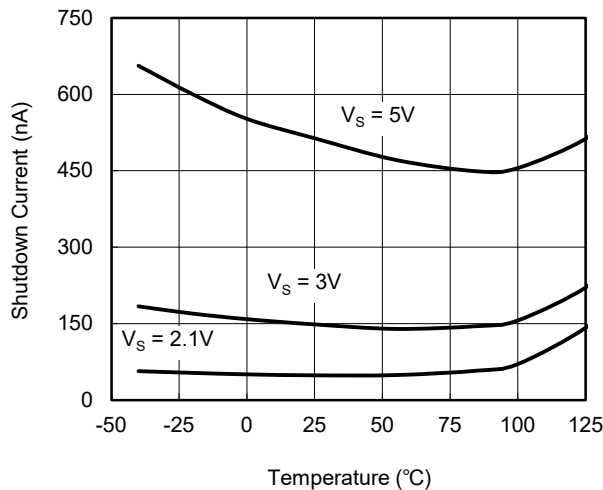
**TYPICAL PERFORMANCE CHARACTERISTICS**

At  $T_A = +25^\circ\text{C}$ ,  $V_{CM} = V_S/2$ ,  $R_L = 600\Omega$ , unless otherwise noted.

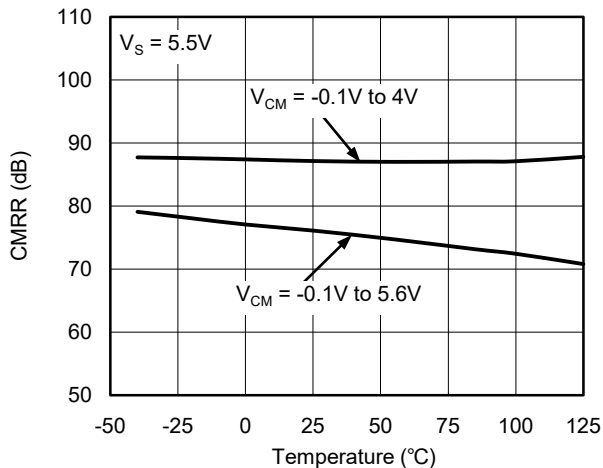
Supply Current vs. Temperature



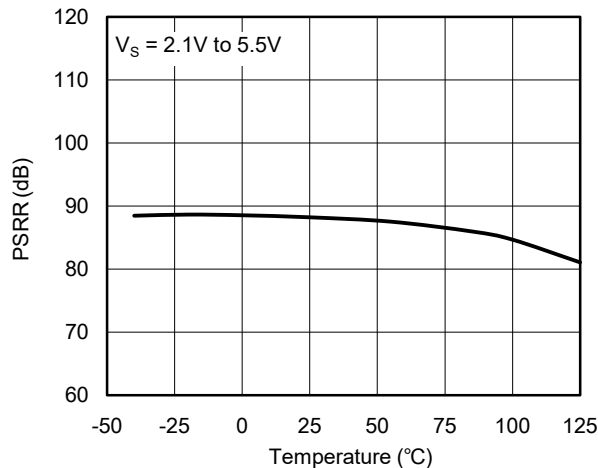
Shutdown Current vs. Temperature



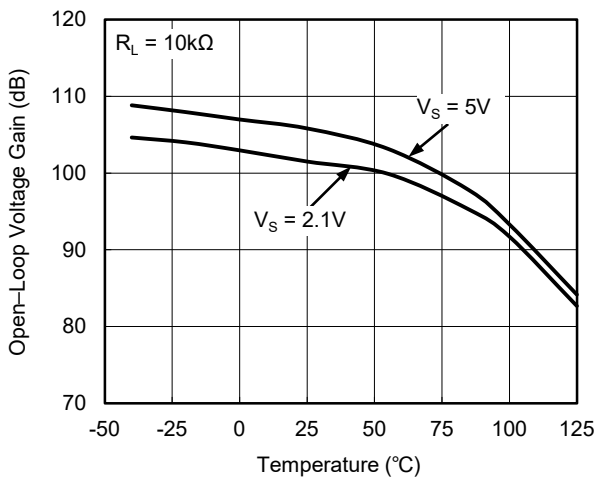
CMRR vs. Temperature



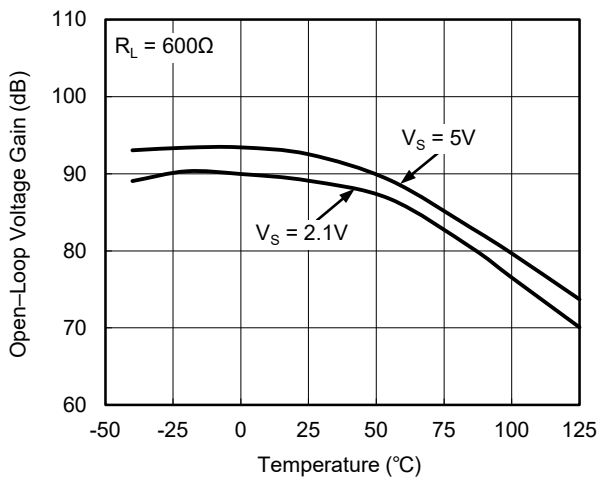
PSRR vs. Temperature



Open-Loop Voltage Gain vs. Temperature

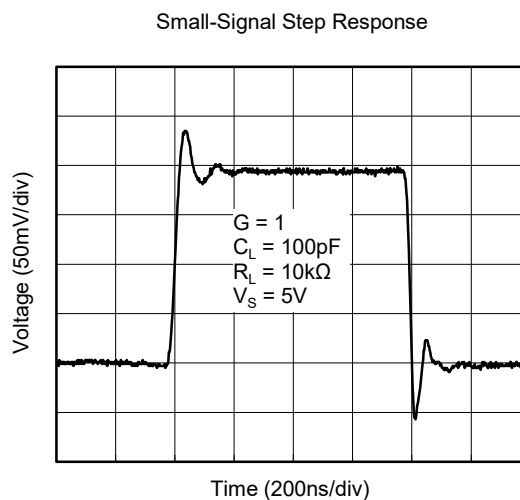
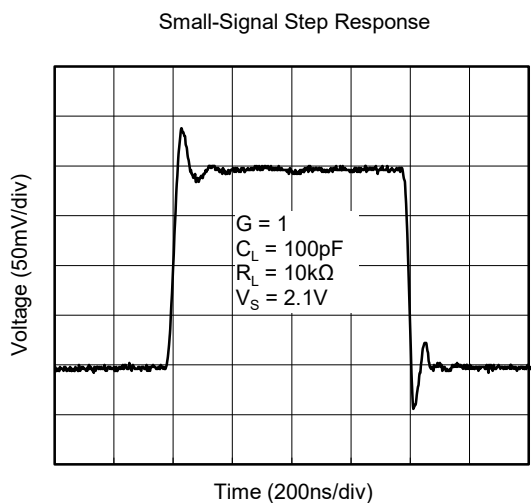
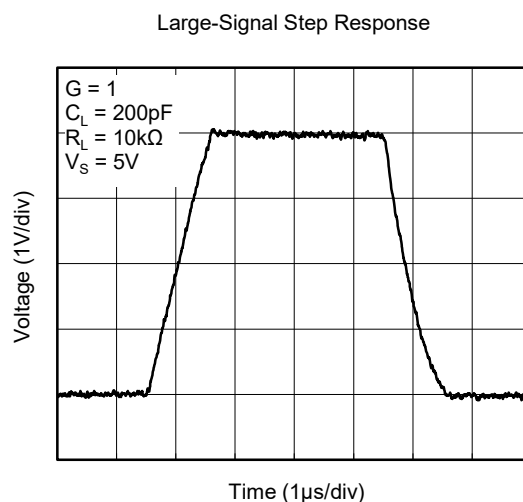
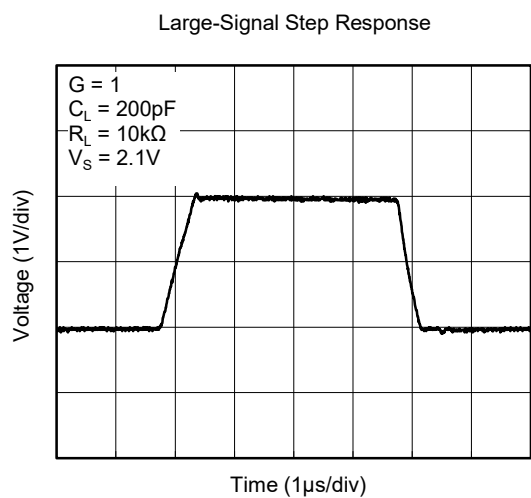
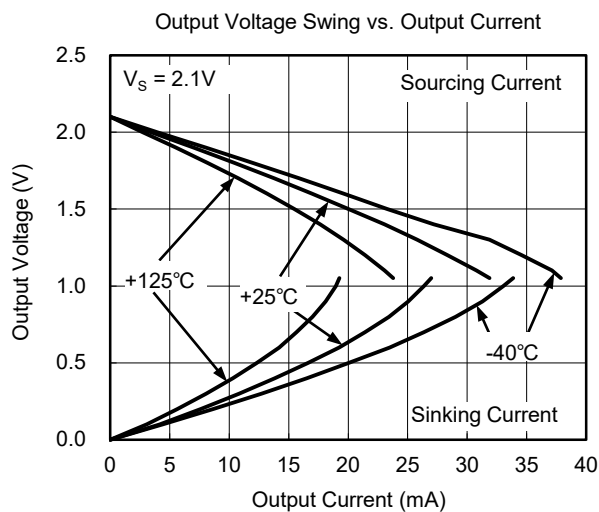
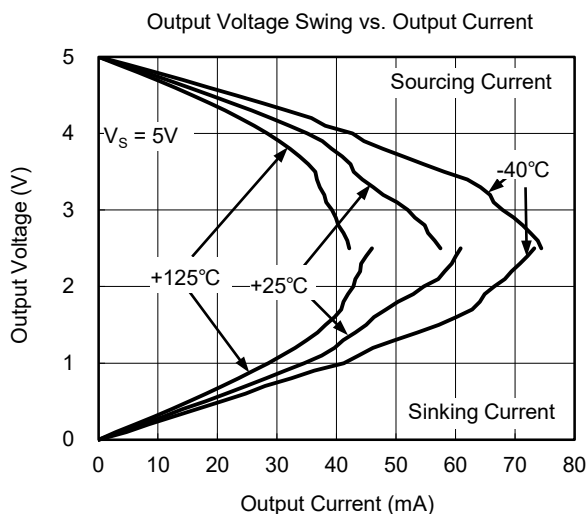


Open-Loop Voltage Gain vs. Temperature



**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

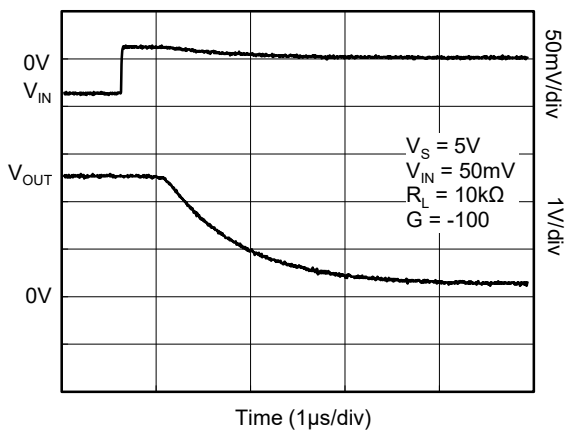
At  $T_A = +25^\circ\text{C}$ ,  $V_{CM} = V_S/2$ ,  $R_L = 600\Omega$ , unless otherwise noted.



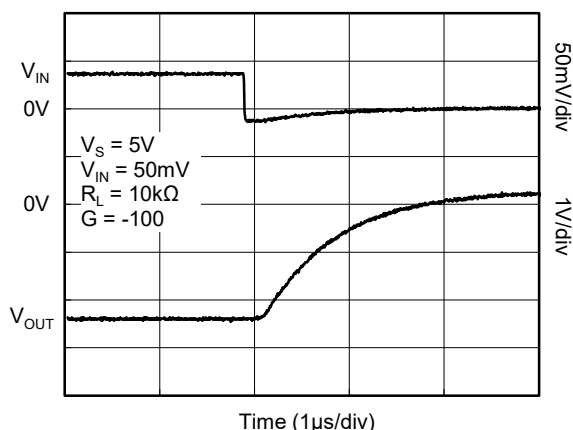
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

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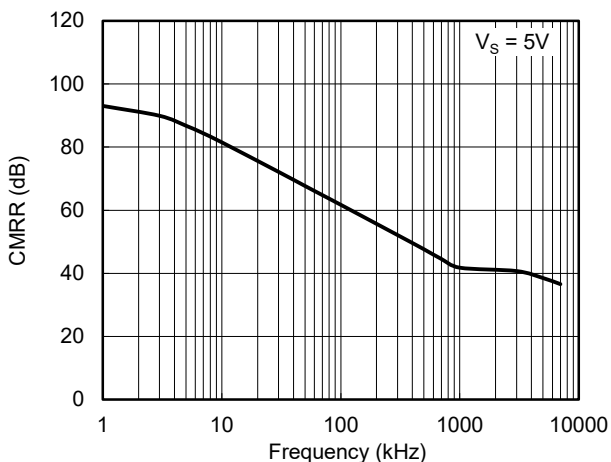
Positive Overload Recovery



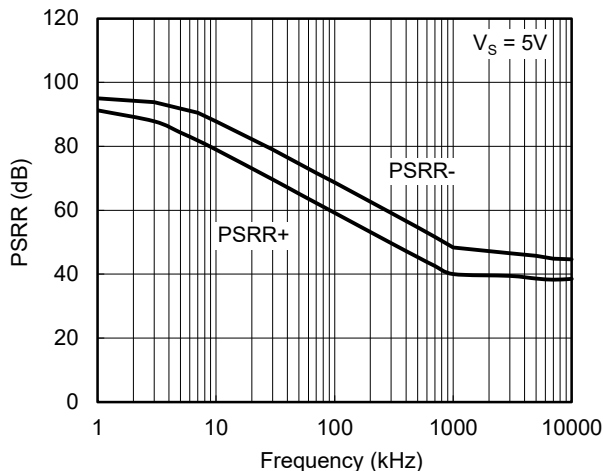
Negative Overload Recovery



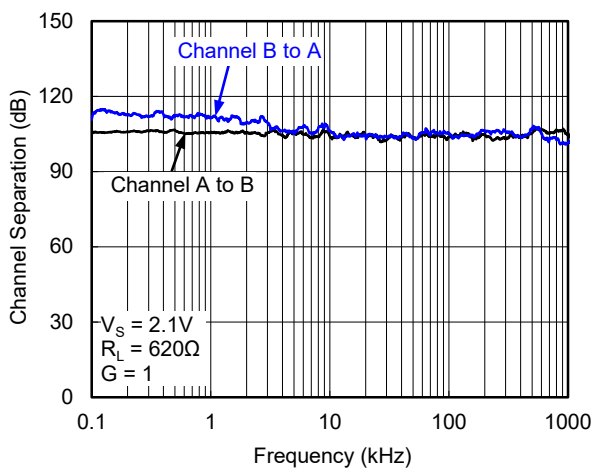
CMRR vs. Frequency



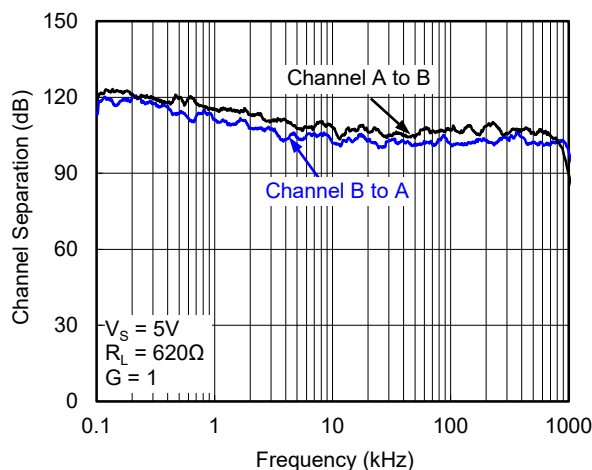
PSRR vs. Frequency



Channel Separation vs. Frequency



Channel Separation vs. Frequency

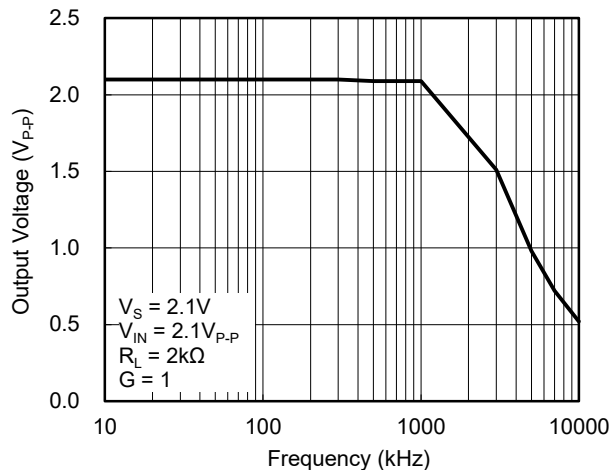




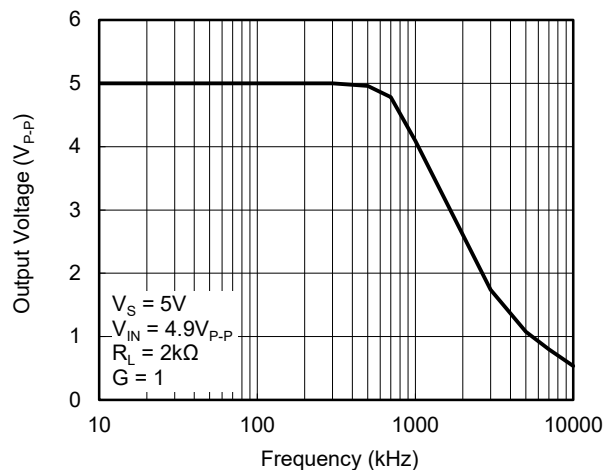
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

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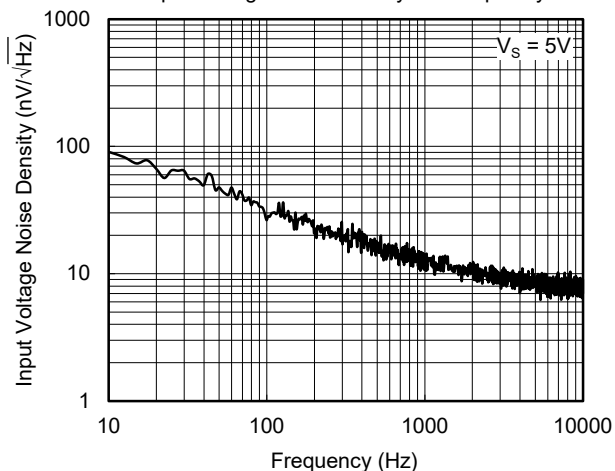
Closed-Loop Output Voltage Swing



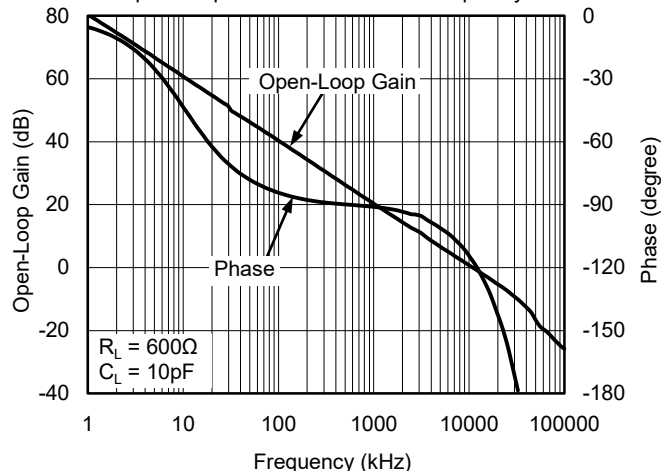
Closed-Loop Output Voltage Swing



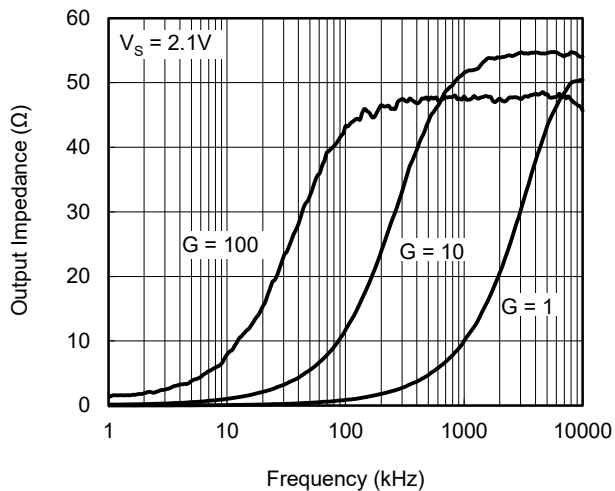
Input Voltage Noise Density vs. Frequency



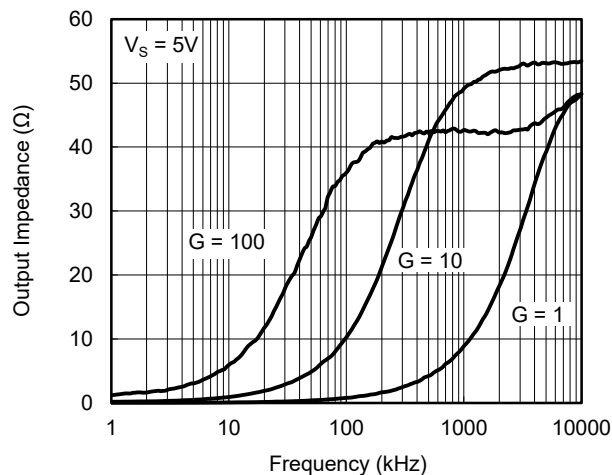
Open-Loop Gain and Phase vs. Frequency



Output Impedance vs. Frequency



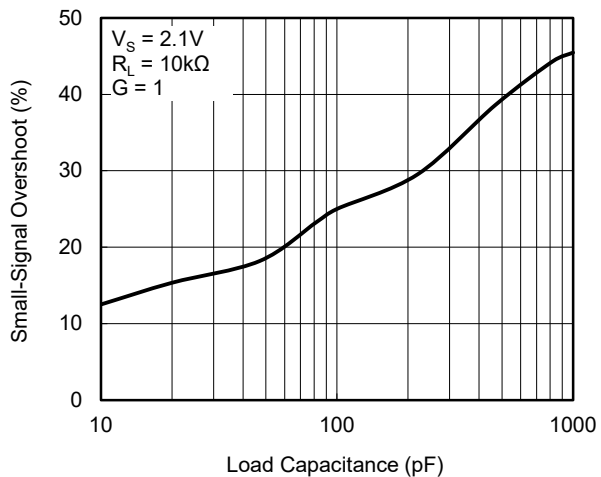
Output Impedance vs. Frequency



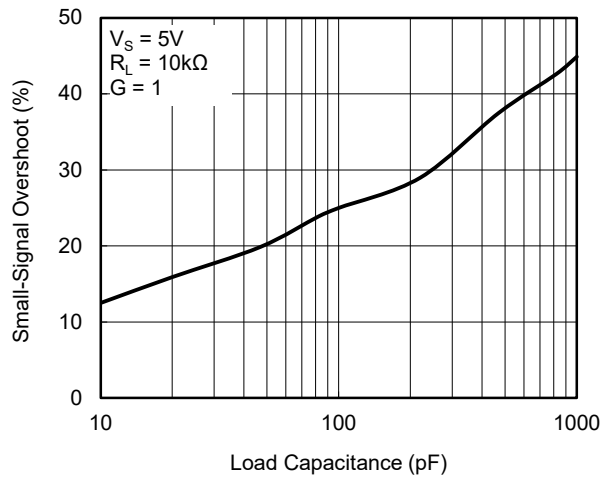
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

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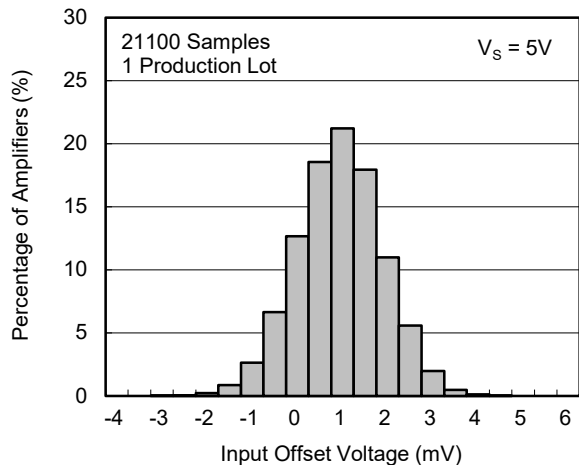
Small-Signal Overshoot vs. Load Capacitance



Small-Signal Overshoot vs. Load Capacitance



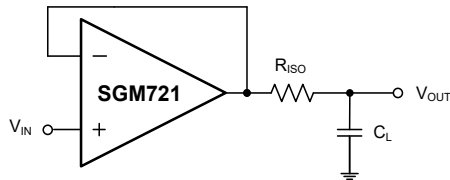
Input Offset Voltage Production Distribution



**APPLICATION NOTES**

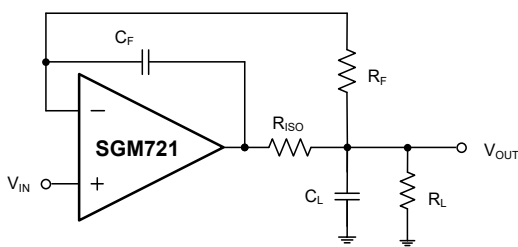
**Driving Capacitive Loads**

The SGM721/2/3/4 can directly drive 4700pF in unity-gain without oscillation. The unity-gain follower (buffer) is the most sensitive configuration to capacitive loading. Direct capacitive loading reduces the phase margin of amplifiers and this results in ringing or even oscillation. Applications that require greater capacitive driving capability should use an isolation resistor between the output and the capacitive load like the circuit in Figure 1. The isolation resistor  $R_{ISO}$  and the load capacitor  $C_L$  form a zero to increase stability. The bigger the  $R_{ISO}$  resistor value, the more stable  $V_{OUT}$  will be. Note that this method results in a loss of gain accuracy because  $R_{ISO}$  forms a voltage divider with the  $R_{LOAD}$ .



**Figure 1. Indirectly Driving Heavy Capacitive Load**

An improved circuit is shown in Figure 2. It provides DC accuracy as well as AC stability.  $R_F$  provides the DC accuracy by connecting the inverting input with the output.  $C_F$  and  $R_{ISO}$  serve to counteract the loss of phase margin by feeding the high frequency component of the output signal back to the amplifier's inverting input, thereby preserving phase margin in the overall feedback loop.



**Figure 2. Indirectly Driving Heavy Capacitive Load with DC Accuracy**

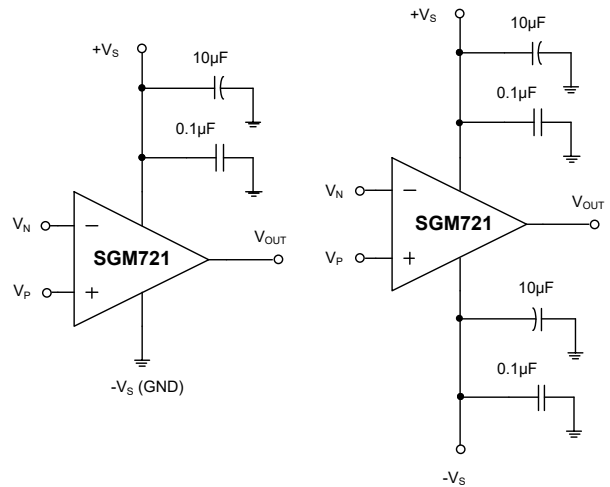
For non-buffer configuration, there are two other ways to increase the phase margin: (a) by increasing the amplifier's closed-loop gain or (b) by placing a capacitor in parallel with the feedback resistor to counteract the parasitic capacitance associated with inverting node.

**Power Supply Bypassing and Layout**

The SGM72x family operates from either a single 2.1V to 5.5V supply or dual  $\pm 1.05V$  to  $\pm 2.75V$  supplies. For single-supply operation, bypass the power supply  $+V_S$  with a 0.1 $\mu F$  ceramic capacitor which should be placed close to the  $+V_S$  pin. For dual-supply operation, both the  $+V_S$  and the  $-V_S$  supplies should be bypassed to ground with separate 0.1 $\mu F$  ceramic capacitors. 2.2 $\mu F$  tantalum capacitor can be added for better performance.

Good PC board layout techniques optimize performance by decreasing the amount of stray capacitance at the operational amplifier's inputs and output. To decrease stray capacitance, minimize trace lengths and widths by placing external components as close to the device as possible. Use surface-mount components whenever possible.

For the operational amplifier, soldering the part to the board directly is strongly recommended. Try to keep the high frequency current loop area small to minimize the EMI (electromagnetic interference).



**Figure 3. Amplifier with Bypass Capacitors**

**Grounding**

A ground plane layer is important for SGM72x circuit design. The length of the current path in an inductive ground return will create an unwanted voltage noise. Broad ground plane areas will reduce the parasitic inductance.

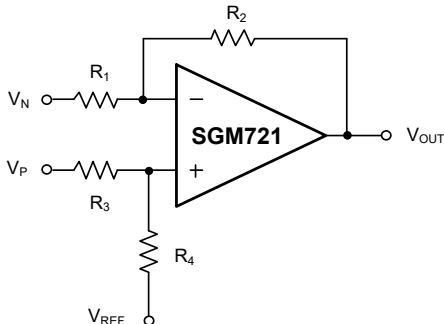
**Input-to-Output Coupling**

To minimize capacitive coupling, the input and output signal traces should not be in parallel. This helps reduce unwanted positive feedback.

**TYPICAL APPLICATION CIRCUITS**

**Differential Amplifier**

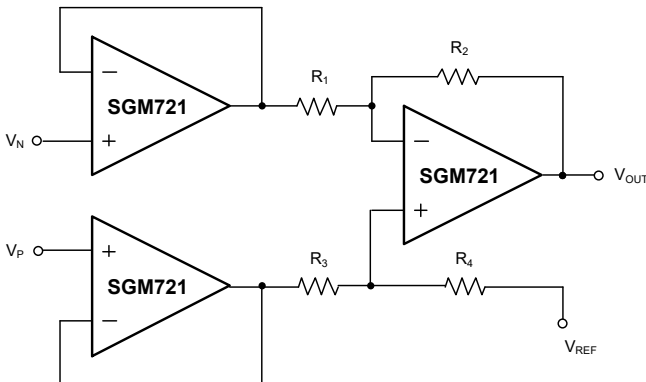
The circuit shown in Figure 4 performs the difference function. If the resistor ratios are equal ( $R_4/R_3 = R_2/R_1$ ), then  $V_{OUT} = (V_P - V_N) \times R_2/R_1 + V_{REF}$ .



**Figure 4. Differential Amplifier**

**Instrumentation Amplifier**

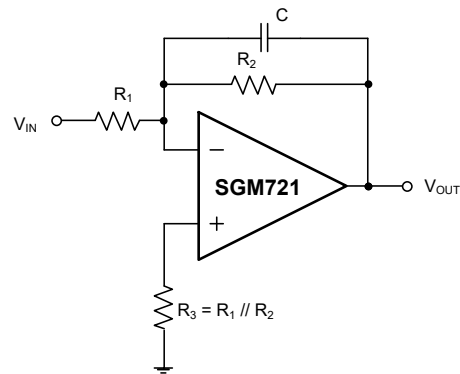
The circuit in Figure 5 performs the same function as that in Figure 4 but with a high input impedance.



**Figure 5. Instrumentation Amplifier**

**Active Low-Pass Filter**

The low-pass filter shown in Figure 6 has a DC gain of  $(-R_2/R_1)$  and the  $-3\text{dB}$  corner frequency is  $1/2\pi R_2 C$ . Make sure the filter bandwidth is within the bandwidth of the amplifier. Feedback resistors with large values can couple with parasitic capacitance and cause undesired effects such as ringing or oscillation in high-speed amplifiers. Keep resistor values as low as possible and consistent with output loading consideration.



**Figure 6. Active Low-Pass Filter**

**REVISION HISTORY**

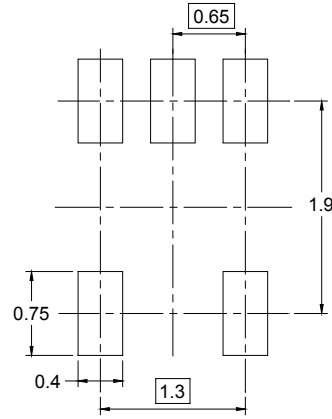
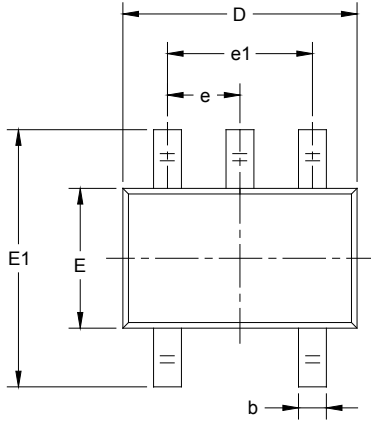
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

JANUARY 2018 – REV.C.1 to REV.C.2	Page
Added Open-Loop Gain and Phase vs. Frequency .....	9
SEPTEMBER 2017 – REV.C to REV.C.1	Page
Changed Supply Voltage .....	2

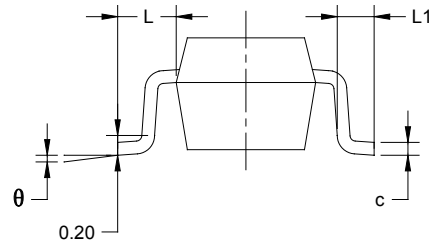
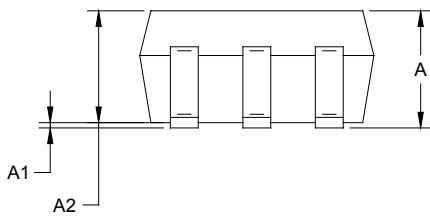
# PACKAGE INFORMATION

## PACKAGE OUTLINE DIMENSIONS

### SC70-5



RECOMMENDED LAND PATTERN (Unit: mm)

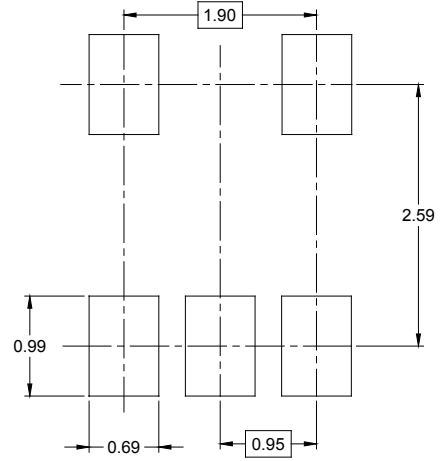
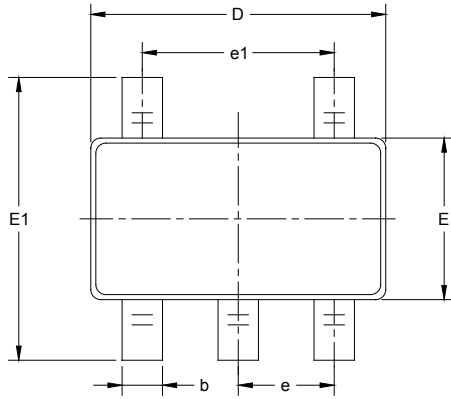


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.65 TYP		0.026 TYP	
e1	1.300 BSC		0.051 BSC	
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
$\theta$	0°	8°	0°	8°

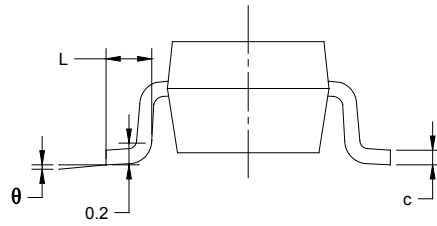
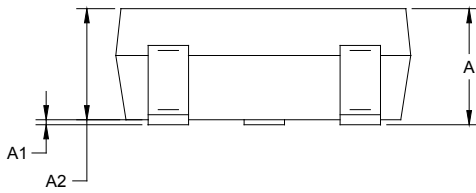
# PACKAGE INFORMATION

## PACKAGE OUTLINE DIMENSIONS

### SOT-23-5



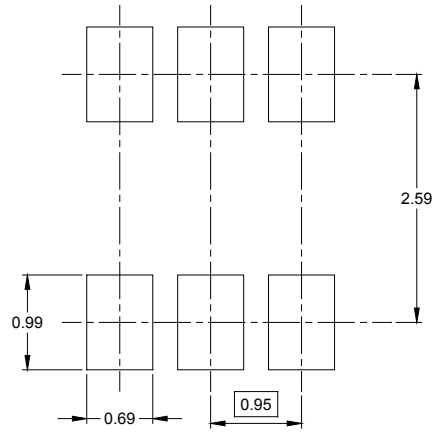
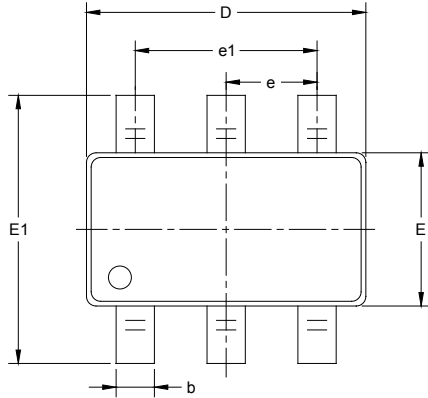
RECOMMENDED LAND PATTERN (Unit: mm)



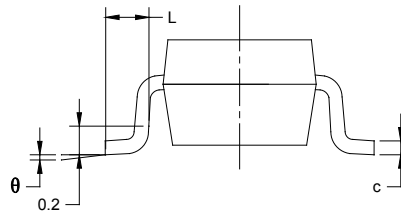
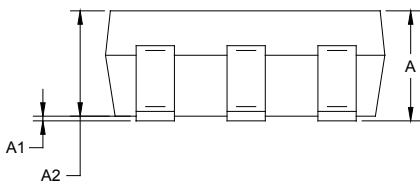
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 BSC		0.037 BSC	
e1	1.900 BSC		0.075 BSC	
L	0.300	0.600	0.012	0.024
$\theta$	0°	8°	0°	8°

PACKAGE OUTLINE DIMENSIONS

SOT-23-6



RECOMMENDED LAND PATTERN (Unit: mm)



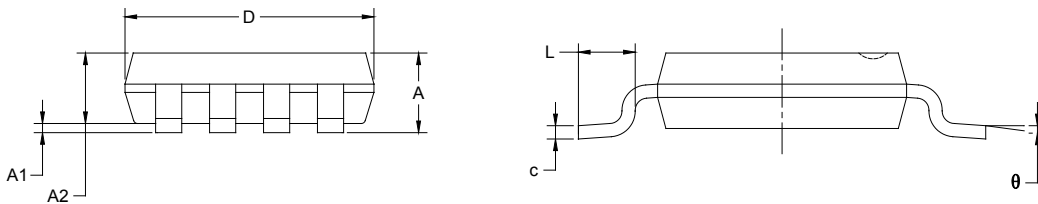
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 BSC		0.037 BSC	
e1	1.900 BSC		0.075 BSC	
L	0.300	0.600	0.012	0.024
$\theta$	0°	8°	0°	8°

PACKAGE OUTLINE DIMENSIONS

MSOP-8



RECOMMENDED LAND PATTERN (Unit: mm)

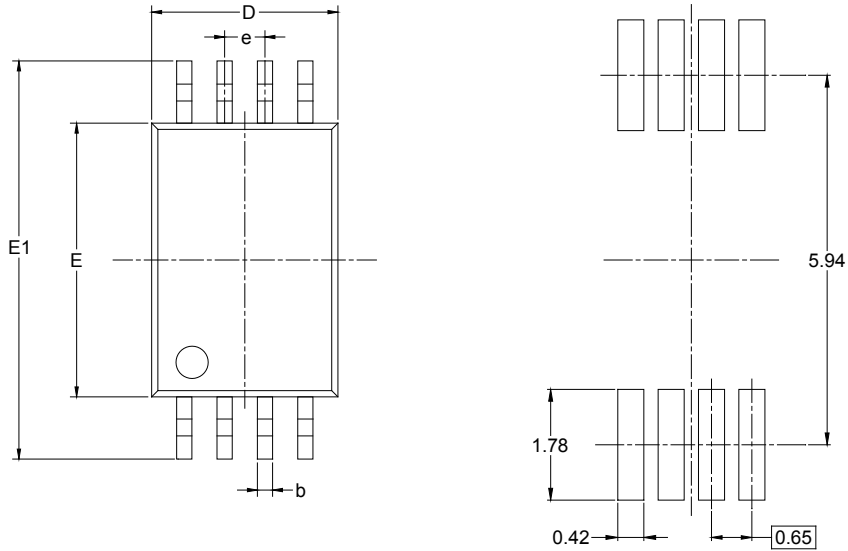


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D	2.900	3.100	0.114	0.122
E	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
e	0.650 BSC		0.026 BSC	
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

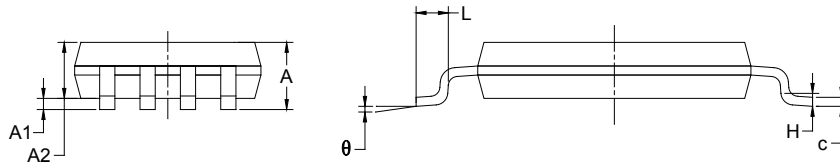


PACKAGE OUTLINE DIMENSIONS

TSSOP-8



RECOMMENDED LAND PATTERN (Unit: mm)

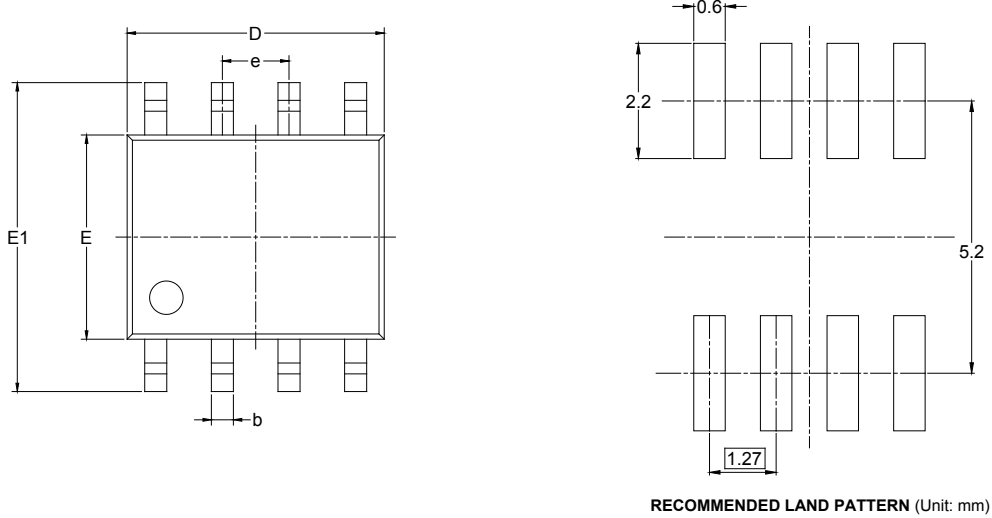


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A		1.100		0.043
A1	0.050	0.150	0.002	0.006
A2	0.800	1.000	0.031	0.039
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D	2.900	3.100	0.114	0.122
E	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650 BSC		0.026 BSC	
L	0.500	0.700	0.02	0.028
H	0.25 TYP		0.01 TYP	
θ	1°	7°	1°	7°

# PACKAGE INFORMATION

## PACKAGE OUTLINE DIMENSIONS

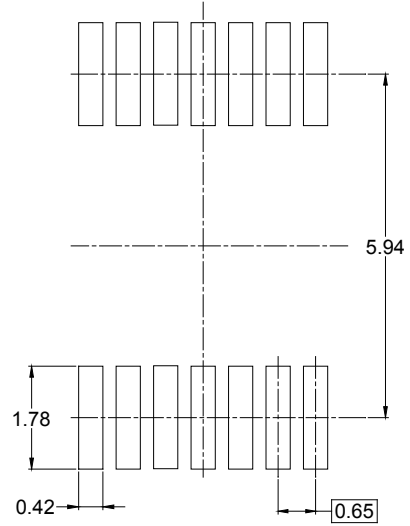
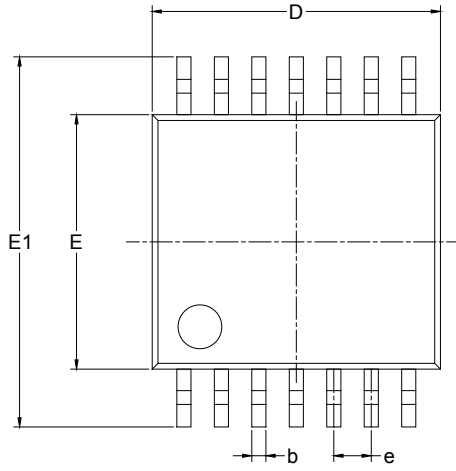
### SOIC-8



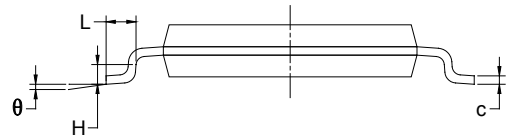
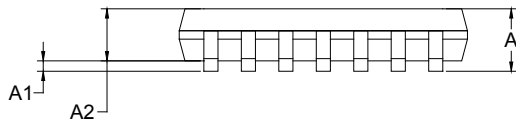
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.27 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
$\theta$	0°	8°	0°	8°

PACKAGE OUTLINE DIMENSIONS

TSSOP-14



RECOMMENDED LAND PATTERN (Unit: mm)

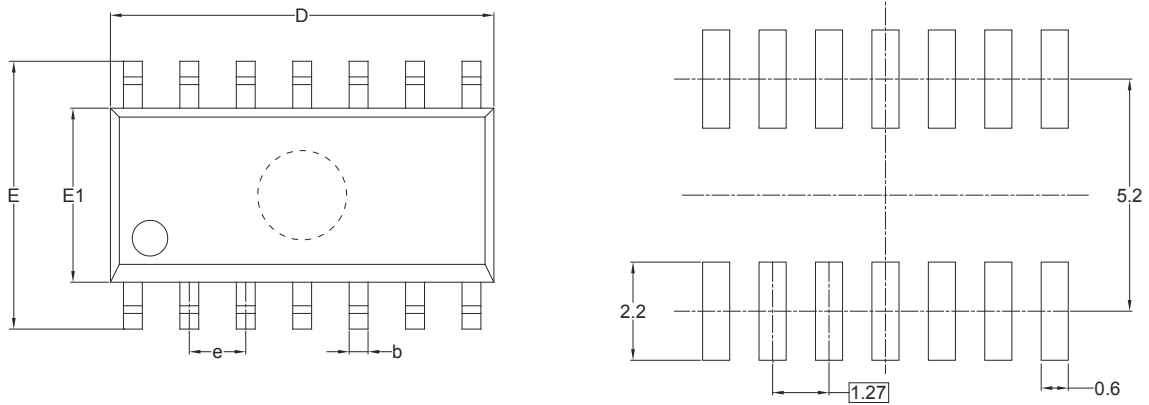


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D	4.860	5.100	0.191	0.201
E	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650 BSC		0.026 BSC	
L	0.500	0.700	0.02	0.028
H	0.25 TYP		0.01 TYP	
$\theta$	1°	7°	1°	7°

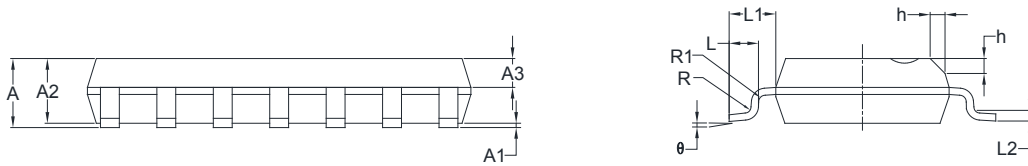
# PACKAGE INFORMATION

## PACKAGE OUTLINE DIMENSIONS

### SOIC-14



RECOMMENDED LAND PATTERN (Unit: mm)

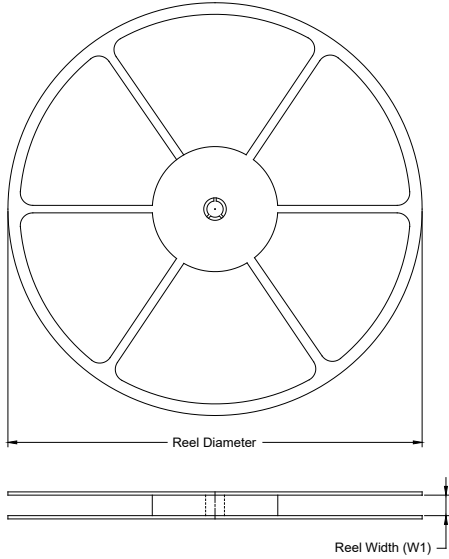


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
A2	1.25	1.65	0.049	0.065
A3	0.55	0.75	0.022	0.030
b	0.36	0.49	0.014	0.019
D	8.53	8.73	0.336	0.344
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
L	0.45	0.80	0.018	0.032
L1	1.04 REF		0.040 REF	
L2	0.25 BSC		0.01 BSC	
R	0.07		0.003	
R1	0.07		0.003	
h	0.30	0.50	0.012	0.020
θ	0°	8°	0°	8°

# PACKAGE INFORMATION

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SC70-5	7"	9.5	2.25	2.55	1.20	4.0	4.0	2.0	8.0	Q3
SOT-23-5	7"	9.5	3.2	3.2	1.4	4.0	4.0	2.0	8.0	Q3
SOT-23-6	7"	9.5	3.17	3.23	1.37	4.0	4.0	2.0	8.0	Q3
SOIC-8	13"	12.4	6.4	5.4	2.1	4.0	8.0	2.0	12.0	Q1
MSOP-8	13"	12.4	5.2	3.3	1.5	4.0	8.0	2.0	12.0	Q1
TSSOP-8	13"	12.4	6.76	3.3	1.8	4.0	8.0	2.0	12.0	Q1
TSSOP-14	13"	12.4	6.95	5.6	1.2	4.0	8.0	2.0	12.0	Q1
SOIC-14	13"	16.4	6.6	9.3	2.1	4.0	8.0	2.0	16.0	Q1

D00001

# PACKAGE INFORMATION

## CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

## KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18
13"	386	280	370	5

DD0002